



Laird™ Tflex™ B200

Tflex B200 is a reliable, compliant thermal interface material offering good thermal performance and easier handling and features a range of multiple surface and enforcement options for a variety of applications. This gap filler’s low modulus interface and softness relieves mechanical stress and reduces thermal resistance. Tflex B200 helps absorb shock, resulting in improved device reliability over the long term. It has high dielectric insulation which works to protect against dielectric breakdown in or between devices. Tflex B200 as a standard product is naturally tacky on both sides and requires no additional adhesive coating to inhibit thermal performance. Tflex B200MFG, an option featuring fiberglass in the middle, has strong tensile and both sides exhibit tackiness properties. This helps prevent deforming during manual or automated assembly. Tflex B200FG, has fiberglass enforcement located near one side. It offers a higher deflection than the B200MFG option, and provides protection close to one side.

TECHNICAL DATA SHEET | (EFFECTIVE 24FEB25)

Laird™ Tflex™ B200			
PHYSICAL PROPERTY	TEST METHOD	UNIT	VALUE
Construction & Composition		-	Ceramic filled silicone sheet
Color		-	grey
Thickness Range		mm	1 - 5
Thermal Conductivity	ASTM D5470	w/mk	2.0
Density	Helium Pyncometer	g/cc	2.2
Thermal Resistance (1.0mm) @ 10 psi, 50°C	ASTM D5470	cin²/w	1.10
Outgassing TML	ASTM E595	%	0.32
Temperature Range	Laird Test Method	°C	-40 to 150
Hardness Shore 00 (3 sec)	ASTM 2240	-	42
UL Flammability Rating	UL 94	-	V-0
Volume Resistivity	ASTM D257	Ω-cm	2 × 10 ¹³